

IN THE CLAIMS:

Kindly amend claims 6-10 as follows:

1. (Allowed) A photosolder resist composition containing (A) a resin containing radical polymerization groups and carboxyl groups obtained by adding a cyclic ether group of a cyclic ether group-containing vinyl monomer to a carboxylic group of a radical copolymer containing at least isobornyl (meth) acrylate and a carboxyl group-containing vinyl monomer as monomer units; (B) an inorganic filler; and (C) a photocurable mixture of a polyfunctional acrylic monomer (c1), a cyclic ether group-containing compound (c2), and a photopolymerization initiator (c3).

2. (Allowed) The photosolder resist composition according to claim 1, wherein said resin (A) has double bonds of 0.1×10^{-3} to 3.0×10^{-3} mol/g and the content of the carboxyl group of 30 to 200 mgKOH/g.

3. (Allowed) The photosolder resist composition according to claim 1, wherein the ratio of the carboxyl group in said resin (A) and the cyclic ether group in said photocurable mixture (C) is (1.3/0.7) to (0.7/1.3) by mole ratio.

4. (Allowed) The photosolder resist composition according to claim 1 further containing a coloring pigment.

5. (Allowed) The photosolder resist composition according to claim 1, wherein the content of said inorganic filler (B) is 5 to 75 parts by weight in 100 parts by weight of solid content of the entire photosolder resist composition.

6. (Currently Amended) ~~The~~ An aqueous emulsion ~~type~~ photosolder resist composition according to ~~claim 1~~, wherein obtained by neutralizing said resin (A) according to claim 1 is

neutralized by with a base ~~and made to be~~ water-soluble.

7. (Currently Amended) The aqueous emulsion ~~type~~ photosolder resist composition according to claim 6, wherein said resin (A) has double bonds of 0.1×10^{-3} to 3.0×10^{-3} mol/g and the content of the carboxyl group of 30 to 200 mgKOH/g.

8. (Currently Amended) The aqueous emulsion ~~type~~ photosolder resist composition according to claim 6, wherein the said ratio of the carboxyl group in said resin (A) and cyclic ether group in said photocurable mixture (C) is (1.3/0.7) to (0.7/1.3) by mole ratio.

9. (Currently Amended) The aqueous emulsion ~~type~~ photosolder resist composition according to ~~claims~~ claim 6, further containing a coloring pigment.

10. (Currently Amended) The aqueous emulsion ~~type~~ photosolder resist composition according to claim 6, wherein the content of said inorganic filler (B) is 5 to 75 parts by weight in 100 parts by weight of solid content of the entire photosolder resist composition.

11. (Allowed) A solder resist film obtained by applying the photosolder resist composition according to claim 1 to a substrate, drying at 50 to 90 °C, exposing by activation energy beam, removing and developing non-exposed parts with an alkaline washing solution, and heating and curing the photocurable parts at 140 to 170 °C.

12. (Withdrawn) A solder resist film obtained by applying the photosolder resist composition according to claim 6 to a substrate, drying at 50 to 90 °C, exposing by activation energy beam, removing and developing non-exposed parts with an alkaline washing solution, and heating and curing the photocurable parts at 140 to 170 °C.